,								·	
AMENI Applicant(s):	OMENT	TRANSMI	6		w . kg	Entity)			Docket No. IIZ.003D2
		ng Date FB 3 Day		To know to	Examiner F. Toledo			Group Art Unit 2823	
Invention: SEM	IICOND	UCTOR APPA			HOD FOI	R FABRICAT	ING	THE SAM	ME (To be Amended)
Transmitted herev		ı amendment ir		entifie	d applica		ENT	<u>S:</u>	
			CLAIM	S AS A	AMENDE	D			
		REMAINING AMENDMENT	HIGHEST # PREV. PAID FOR		ŀ	BER EXTRA		RATE	ADDITIONAL FEE
TOTAL CLAIMS	7		20	=		0	х	\$18.00	
INDEP. CLAIMS	2		3	=		0	х	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable)									\$0.00
			TOTAL ADDIT	IONA	LFEEF	OR THIS AME	END	MENT	\$0.00
Please chat A duplicate A check in The Communicate A duplicate A duplicate A Any a	arge Depe e copy of the amonissioner ation or ce copy of dditional atent app	required for a posit Account Not this sheet is equit of is hereby authoredit any overpositions fees required filing fees required for a feet feet for a feet feet feet feet feet feet feet fe	to. nclosed. to cover to cover to cover to cover to chargo ayment to Denclosed. sired under 37	ge pay posit A C.F.R er 37 (ng fee is yment of Account R. 1.16. CFR 1.1	No. 50-0238		associate	RECEIVED FEB -5 2003 WITH TECHNOLOGY CENTER 28
VOLENTINE FRANCOS, P.L.L.C. 2200 SUNRISE VALLEY DRIVE, SUITE 150 RESTON, VA 20191 TEL. NO. (703) 715-0870						I certify that this document and fee & being deposited on with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231. Signature of Person Mailing Correspondence			
c:						Typed or Print	ted No	ame of Perso	on Mailing Correspondence





IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Takashi Ohsumi

Group Art Unit: 2823

Serial No.: 09/920,713

Examiner: F. Toledo

Filed: August 3, 2001

For:

SEMICONDUCTOR APPARATUS AND METHOD FOR FABRICATING

THE SAME (To Be Amended)

AMENDMENT

Honorable Assistant Commissioner for Patents Washington, D.C. 20231

Date: February 3, 2003

Sir:

In response to the Office Action dated November 6, 2002, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

In the Title:

Please amend the title to read --A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS--.

In the Abstract:

Please cancel the Abstract and replace with the Abstract attached herewith.